HPC & Manufacturing A partly-research focused view from NIST

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CHIPS Act



chips.gov

A Message from the Secretary of Commerce Funding Opportunities Research and Development Programs National Security Workforce Development News & Releases Webinars & Events Current CHIPS Job Openings Implementation Strategies







DoE – HPC 4 Mfg

Office of Advanced Manufacturing (OAM)



• CHIPS & Science Act: up to 3 semiconductor institutes

About Manufacturing USA

VISION: Securing U.S. Global Leadership in Advanced Manufacturing

MISSION: Connecting people, ideas, and technology to:

- solve industry-relevant advanced manufacturing challenges
- enhance industrial competitiveness and economic growth
- strengthen our national security





Manufacturing USA Network



NIST Hollings Manufacturing Extension Partnership (MEP)

- MEP National Network
 - Local & State Manufacturing Institutes
- https://www.nist.gov/mep
- Supplier Scouting
- Finding & Retaining Talent
- Etc.



NIST Laboratory Programs



Life Sciences Instruments

- High end microscopes
 - Reaches \$350 K!
 - Nikon Live Cell Imaging station (URL)

CT scan machine

Reaches \$1M!

- Supercomputer inside
 - Prediction being realized
 - ▶ 5–10 % of cost



Additive Manufacturing

- Activities in multiple labs
 - Engineering Laboratory (EL)
 - Materials Measurement Laboratory
 - Physical Measurement Laboratory
 - Contact: EL's Yan Lu (yan.lu@nist.gov)
- Research collaboration with EL
 - Real-Time Processing
 - UMD's Prof. S. Bhattacharyya + students
 - Image Analytics
 - Material Point Methods
 - Utah's Prof. M. Berzins & Sree Kadiyala



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Additive Manufacturing Metrology Testbed (AMMT)



Problems

- Unevenly spread powder leads to ridges and valleys.
- Melt pool sparks leads to divots and depositing material in other locations.

Solution

- Detect defects with CT scan after manufacturing
 - Requires waiting for part to be complete
- Detect defects during manufacture
 - Abort, fix by remelting, or avoid by adjusting laser power or respreading

Additive Manufacturing + HPC



Laser Sintering — Keyholing and Spatter





- Keyhole fluctuations and underlying physics (growth, shrinkage, collapse, etc.) are not fully understood.
- Combine mathematical models, surrogate models, and real-world experimental data to gain insights into the physics of keyholing and defect formation.

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Material Point Method + HPC

Material Point Method

- Discretized by Lagrangian particles over fixed Eulerian background grid.
- Robust for multi-phase interactions.
- Computationally expensive.

Solution

- Highly optimized GPU MPM code
- Use Hedgehog + cluster to simulate complex multi-physics phenomena (melt pool behavior).

